Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



**.014”**

**.014”**

**Top Material: Au**

**Backside Material: AuAs**

**Bond Pad Size: .003” X .003”**

**Backside Potential: COLLECTOR**

**Mask Ref: 0213**

**APPROVED BY: DK DIE SIZE .014” X .014” DATE: 9/23/21**

**MFG: PHILIPS THICKNESS .008” P/N: BFR96**

**DG 10.1.2**

#### Rev B, 7/1